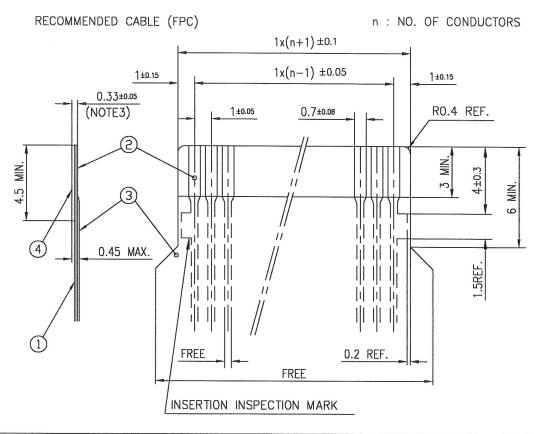


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PT. NO.	DESCRIPTION	MATERIAL	THICKNESS (µm)		
1	BASE FILM	POLYIMIDE OR POLYESTER OR EQUIVALENT			
2	CONDUCTOR	COPPER FOIL(PLATING : SOLDER 1   m MIN.)	35		
3	OVERLAY	POLYIMIDE OR POLYESTER OR EQUIVALENT			
4 SUPPORTING TAPE		POLYESTER OR POLYIMIDE OR EQUIVALENT	188		

NOTES

- 1. NO BURR AT EACH PORTION.
- 2. NO PEELING IN COMMON USE.
- 3. TOTAL THICKNESS LIMIT OF EACH MATERIAL (INCLUDING ADHESIVE AGENT) IS SPECIFIED.

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